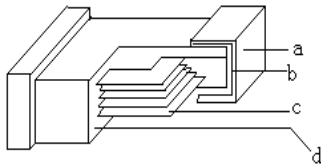




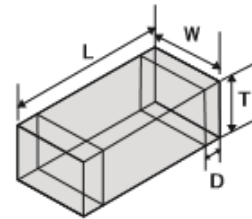
Product Structure



- a. Kx Ag layer
- b. Ni/Sn plating
- c. Inner electrode
- d. Body

Dimension

Part No	L(mm)	W(mm)	T(mm)	D(mm)
160808 (0603)	1.6± 0.20 (0.063± 0.008)	0.8± 0.20 (0.031± 0.008)	0.8± 0.20 (0.031± 0.008)	0.3± 0.2 (0.01± 0.008)
201209 (0805)	2.0± 0.20 (0.079± 0.008)	1.2± 0.20 (0.047± 0.008)	0.9± 0.20 (0.035± 0.008)	0.5± 0.3 (0.020± 0.012)
201609 (0806)	3.2± 0.20 (0.079± 0.008)	1.6± 0.20 (0.063± 0.008)	0.9± 0.20 (0.035± 0.008)	0.5± 0.3 (0.020± 0.012)
252010 (1008)	2.5± 0.20 (0.098± 0.008)	2.0± 0.20 (0.079± 0.008)	1.0± 0.20 (0.039± 0.008)	0.5± 0.3 (0.020± 0.012)



Electrical Characteristics

1608 Type

Part NO	Tolerance	Inductance $\mu$	Test frequency(MHz)	$Q$	SRF(MHZ)min	$I_r$ (mA)Max
CMH160808BR47MT	± 20%	0.047	1	0.10±30%	100	1050
CMH160808BR56MT	± 20%	0.056	1	0.12±30%	100	1050
CMH160808B1R0MT	± 20%	1.0	1	0.20±30%	98	900
CMH160808B1R8MT	± 20%	1.8	1	0.24±30%	95	750
CMH160808B2R2MT	± 20%	2.2	1	0.24±30%	95	750
CMH160808B4R7MT	± 20%	4.7	1	0.50±30%	65	700

2012 Type

Part NO	Tolerance	Inductance $\mu$	Test frequency(MHz)	$Q$	SRF(MHZ)min	$I_r$ (mA)Max
CMH201209A1R0MT	± 20%	1.0	1	0.14±25%	75	300
CMH201209A2R2MT	± 20%	2.2	1	0.224±25%	50	220
CMH201209A3R3MT	± 20%	3.3	1	0.24±25%	35	200
CMH201209A4R7MT	± 20%	4.7	1	0.30±25%	25	180



Part NO	Tolerance	Inductance H	Test frequency(MHz)		SRF(MHZ)min	Ir (mA)Max
CMH201209B1R0MT	± 20%	1.0	1	0.11±25%	75	1150
CMH201209B2R2MT	± 20%	2.2	1	0.20±25%	50	950
CMH201209B3R3MT	± 20%	3.3	1	0.22±25%	35	800
CMH201209B4R7MT	± 20%	4.7	1	0.30±25%	25	750
CMH201209B6R8MT	± 20%	6.8	1	0.30±25%	25	600

2016 Type

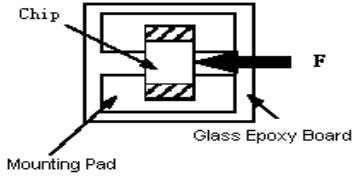
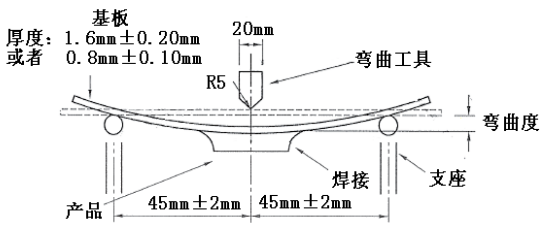
Part NO	Tolerance	Inductance H	Test frequency(MHz)		SRF(MHZ)min	Ir (mA)Max
CMH201609B1R0MT	± 20%	1.0	1	0.10±25%	70	1400
CMH201609B2R2MT	± 20%	2.2	1	0.16±25%	50	1200
CMH201609B3R3MT	± 20%	3.3	1	0.20±25%	40	1200
CMH201609B4R7MT	± 20%	4.7	1	0.26±25%	30	1100

2520 Type

Part NO	Tolerance	Inductance H	Test frequency(MHz)		SRF(MHZ)min	Ir (mA)Max
CMH252010B1R0MT	± 20%	1.0	1	0.06±25%	70	1600
CMH252010B2R2MT	± 20%	2.2	1	0.10±25%	55	1300
CMH252010B3R3MT	± 20%	3.3	1	0.14±25%	30	1200
CMH252010B4R7MT	± 20%	4.7	1	0.18±25%	25	1100

Reliability Test Method

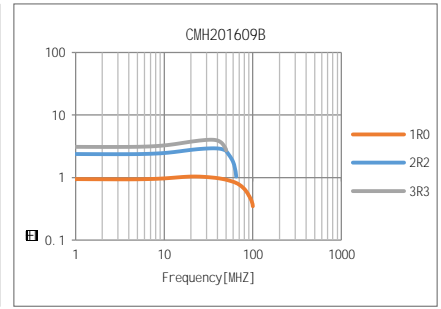
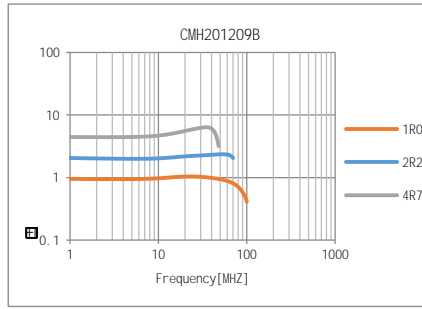
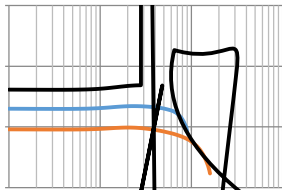
Item No.	Items	Requirements	Test Methods and Remarks
1	Operating Temperature Range	-	/
	Solder ability	95% or more of electrode area shall be coated by new solder.	<p>           : 120 ~ 150            : 60s            96.5%Sn/3.0%Ag/0.5%Cu            : 245±5            : 10mm            : 5f 1s            : 3 ~ 5 s            Preheating temperature: 120°C to 150°C            Preheating time: 60s            Solder 96.5%Sn/3.0%Ag/0.5%Cu of the Sn solder.            Solder temperature: 245±5°C            Immersion tin depth: 10mm            Duration : 5±1s            Dip performance to a flux of about: 3 ~ 5 s         </p>

No.	Items	Requirements	Test Methods and Remarks
	Resistance to Soldering Heat	95%  (B ): 30% (A ): 30%At least  95% of terminal electrode should be covered with solder. No mechanical damage. Inductance : B: change within $\pm 30\%$ A: change within $\pm 30\%$	: 120 -150 : 60s 96.5%Sn/3.0%Ag/0.5%Cu : 260 5 :10mm : 10 1s :3 5 s  Preheating temperature: 120°C to 150°C Preheating time: 60s Solder 96.5%Sn/3.0%Ag/0.5%Cu of the Sn solder. Solder temperature: 260°C $\pm$ 5°C Immersion tin depth:10mm Duration : 10 $\pm$ 1s Dip performance to a flux of about:3~5 s
	Adhesion of electrode	The termination and body should be no damage.	11608 7N 2012 2016 2520 10N  Applied force: 7N force for 1608 series; 10N force for 2012、2016、2520 series. Keep time : 10 $\pm$ 1S  
	Low temperature resistance	10% No mechanical damage. Inductance change: within $\pm 10\%$	: -40 2 : h Temperature: -40 $\pm$ 2°C Testing time: h
	Bending strength	No mechanical damage	: 0.5mm/s, : 2mm, 20s 1s Testing board: glass epoxy-resin substrate For 0.5 mm/s compression speed, curvature: 2mm, hold time 20s $\pm$ 1s 。  



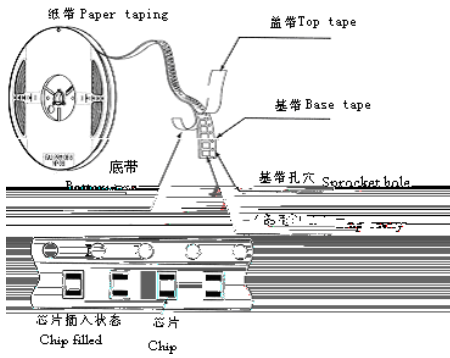
-NCC

Inductance Vs. Frequency Characteristics

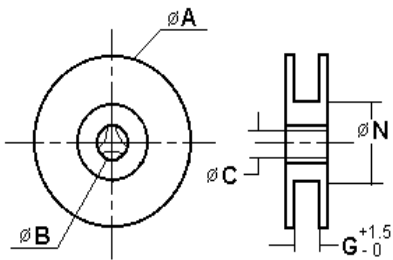


Packaging

\*  Taping drawings

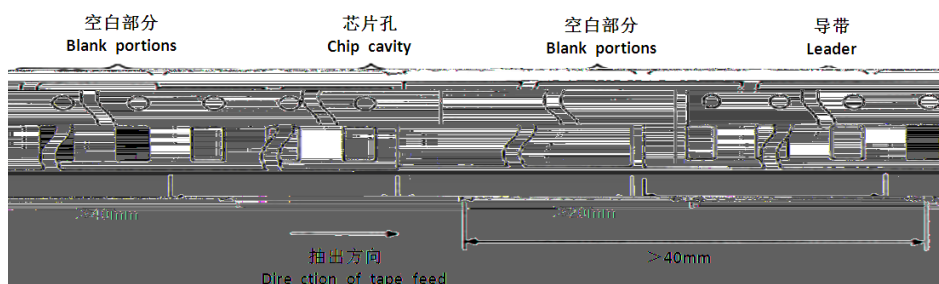


\*  Reel dimensions (Unit: mm)



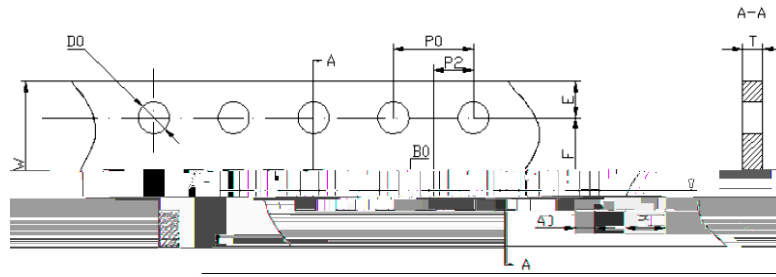
<input type="checkbox"/> Size	A	B	C	N	G
CF-8	178±2.0	22.0±2.0	12.5±1.5	57±2.0	8

\*  Leader and blank portion



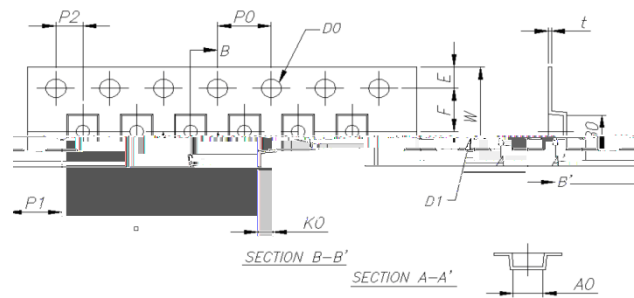
\* □ Taping dimensions (Unit: mm)

⌘ Paper tape



Part NO.	A0	B0	W	F	E	P1	P2	P0	D0	T
160808	1.10±0.2	1.90±0.2	8.0±0.2	3.5±0.1	1.75±0.2	4.0±0.2	2.0±0.1	4.0±0.2	1.55±0.1	0.95±0.1
201209	1.50±0.2	2.30±0.2	8.0±0.2	3.5±0.1	1.75±0.2	4.0±0.2	2.0±0.1	4.0±0.2	1.55±0.1	0.95±0.1
201609	1.85±0.1	2.35±0.1	8.0±0.1	3.5±0.1	1.75±0.2	4.0±0.2	2.0±0.1	4.0±0.2	1.55±0.1	0.95±0.1

⌘, \ Embossed tape



Á Size	252010
W	8.00+/-0.20
E	1.75+/-0.10
F	3.50+/-0.10
D0	1.50+/-0.10
D1	1.00+/-0.10
P0	4.00+/-0.10
P010	40.0+/-0.20
P1	4.00+/-0.10
P2	2.00+/-0.10
A0	2.20+/-0.10
B0	2.75+/-0.10
K0	1.05+/-0.10
t	0.23+/-0.20



\*

Packaging number (Unit: Pcs )

2± Å SIZE	252010	201609	201209	160808
H REEL	3000	4000	4000	4000
"H BOX	30000	40000	40000	40000
1H CASE	180000	240000	240000	240000